L Number	Hits	Search Text	DB	Time stamp
1	6910	438/637.ccls. 438/641.ccls. 438/667.ccls. 438/675.ccls.	USPAT;	2004/11/08 14:55
		438/678.ccls. 438/686.ccls. 427/97.ccls. 427/110.ccls.	US-PGPUB	
		427/125.ccls. 427/191.ccls. 427/192.ccls. 427/236.ccls.		
		427/383.1.ccls. 427/422.ccls. 427/455.ccls. 427/597.ccls.		
2	1918	(438/637.ccls. 438/641.ccls. 438/667.ccls. 438/675.ccls.	USPAT;	2004/11/08 14:56
		438/678.ccls. 438/686.ccls. 427/97.ccls. 427/110.ccls.	US-PGPUB	' '
	•	427/125.ccls. 427/191.ccls. 427/192.ccls. 427/236.ccls.	1	
		427/383.1.ccls. 427/422.ccls. 427/455.ccls. 427/597.ccls.) and		
		(aerosol spray\$6 nanoparticle)		
3	27	(438/637.ccls. 438/641.ccls. 438/667.ccls. 438/675.ccls.	USPAT;	2004/11/08 14:59
	_,	438/678.ccls. 438/686.ccls.) and (427/97.ccls. 427/110.ccls.	US-PGPUB	200 1, 22, 00 2 1103
		427/125.ccls. 427/191.ccls. 427/192.ccls. 427/236.ccls.	05 1 0. 05	
		427/383.1.ccls. 427/422.ccls. 427/455.ccls. 427/597.ccls.)		
	88	((aerosol spray\$6 nanoparticle) with (conduct\$6 copper cu	USPAT;	2004/11/08 15:04
4	00	silver ag gold au) with (via hole opening plug seed)) same	US-PGPUB	2004/11/00 13.04
			03-FGF06	,
_	10	(integrated semiconductor memory cell) 5529634.URPN.	USPAT	2004/11/08 15:11
5	10			
6	156	((aerosol spray\$6 nanoparticle) same (conduct\$6 copper cu	EPO; JPO;	2004/11/08 15:12
		silver ag gold au) same (via hole opening plug seed)) and	DERWENT;	
	05	(integrated semiconductor memory cell)	IBM_TDB	2004/11/00 15:40
7	95	1 33 7 7	USPAT;	2004/11/08 15:49
		438/678.ccls. 438/686.ccls. 427/97.ccls. 427/110.ccls.	US-PGPUB	
		427/125.ccls. 427/191.ccls. 427/192.ccls. 427/236.ccls.		
		427/383.1.ccls. 427/422.ccls. 427/455.ccls. 427/597.ccls.) and		
		((aerosol spray\$6 nanoparticle) same (conduct\$6 copper cu		
		silver ag gold au))) and (((integrated adj circuit) ic		
		semiconductor memory cell) same (via hole opening plug		
		seed))	1	
8	111	((maskless adj mesoscale adj2 (materials deposition)) m3d	USPAT;	2004/11/08 16:03
		"m.sup.3d" "m.sup.3 d") and (via plug semiconductor ic	US-PGPUB;	
		(integrated adj circuit)) and (conduct\$6 copper cu silver ag	EPO; JPO;	
		gold au)	DERWENT;	<u>}</u>
			IBM_TDB	
9	10	(memory adj (cell circuit array)) same (column with row with	USPAT;	2004/11/08 16:20
		(decoder address)) same (sensing adj (circuit amplifier)) same	US-PGPUB	
		(via plug)		
10	2	((memory adj (cell circuit array)) same (column with row with	USPAT;	2004/11/08 16:21
		(decoder address)) same (sensing adj (circuit amplifier))) and	US-PGPUB	
		(plug same ((bit adj line) (word adj line) wordline bitline))		
11	9	((aa.) (aa a aa aa/// aaa (aa.a	USPAT;	2004/11/08 16:22
		(decoder address)) same (sensing adj (circuit amplifier))) and	US-PGPUB	ł
		(interconnect\$6 same ((bit adj line) (word adj line) wordline		
	!	bitline))		
12	638	((438/637.ccls. 438/641.ccls. 438/667.ccls. 438/675.ccls.	USPAT;	2004/11/08 16:28
		438/678.ccls. 438/686.ccls. 427/97.ccls. 427/110.ccls.	US-PGPUB	
	:	427/125.ccls. 427/191.ccls. 427/192.ccls. 427/236.ccls.		
	i	427/383.1.ccls. 427/422.ccls. 427/455.ccls. 427/597.ccls.) and	Į	
	1	(aerosol spray\$6 nanoparticle)) and (integrated semiconductor		
	:	memory cell)	`	